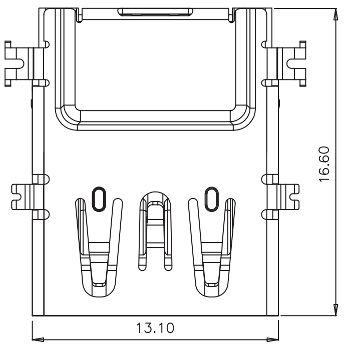
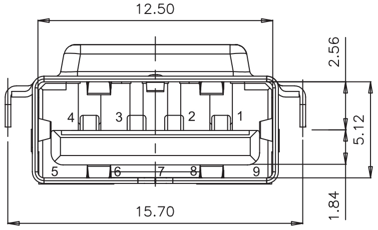
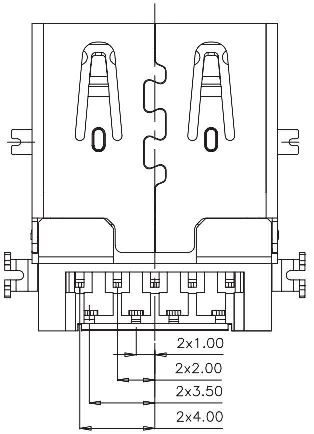
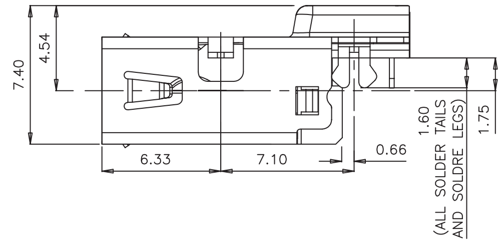
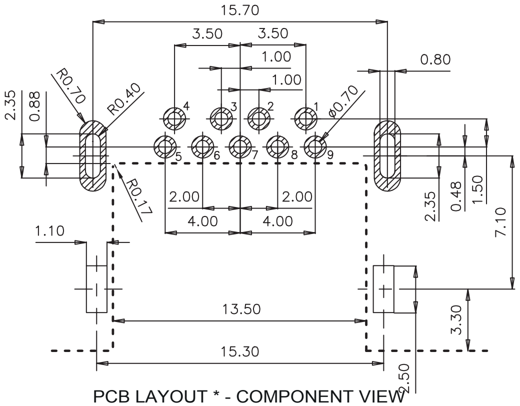










PCB LAYOUT * - COMPONENT VIEW

TECHNICAL CHARACTERISTICS

MATERIAL
INSULATOR: LCP
FLAMABILITY RATING: UL94-V0
COLOR: BLUE
CONTACT MATERIAL: PHOSPHORE BRONZE
CONTACT TYPE: STAMPED
CONTACT PLATING: UNDERPLATE 1.27 to 2.54 µm Ni
CONTACT AREA 0.76 µm Gold
SOLDER TAIL AREA 2.54 to 5.08 µm Matt Tin
SHIELDING: BRASS MATT TIN PLATED

ENVIRONMENTAL
OPERATING TEMPERATURE: -20 up to +85°C
COMPLIANCE: RoHS & LEAD FREE AS PER DIRECTIVE 2002/95/EC
HALOGEN FREE COMPLIANT AS PER IEC 61249-2-21

ELECTRICAL
CURRENT RATING:
- PIN 1 & PIN 4 (Vbus & corresponding ground PIN) 1.8A Max
- OTHER PINS 0.25 A Max
WORKING VOLTAGE: 30Vac
DIELECTRIC WITHSTANDING VOLTAGE: 100Vac/min
INSULATION RESISTANCE: > 100MΩ
CONTACT RESISTANCE:
- PIN 1 & PIN 4: 30mΩ Max
- OTHER PINS: 50mΩ Max
IMPEDANCE: 90Ω +/- 15Ω @ 50ps RISE TIME (20~80%)

STANDARD
UL CERTIFIED: E323964 / MODEL NUMBER 692121330100

MECHANICAL
INSERTION FORCE: 35.0N Max
EXTRACTION FORCE: 10.0N min
QUALITY CLASS: 5000 MATING CYCLES

SOLDERING
REFLOW PROCESS ONLY AS PER JEDEC J-STD-020D

PACKAGING
TAPE & REEL

* NOTE: THE RECOMMENDED PCB LAYOUT IS FOR AN OPTIMIZED RETENTION FORCE OF CONNECTOR ON PCB BUT IT IMPLIES INSERTION FORCE THAT A LOT OF PICK AND PLACE MACHINES ARE NOT ABLE TO HANDLE. THEREFORE IT MIGHT BE NECESSARY TO DRILL BIGGER HOLES FOR THE CLIPS. PLEASE CHECK THIS CARFULLY.

RoHS Compliant

REV	DATE	FILE	BY
G			
F			
E	09-NOV-11	STENCIL	GG
D	21-SEP-11	NOTE	GG
C	10-MAY-11	UL	GG
B	02-MAY-11	DIMENSION	GG
A	04-AUG-10	PDF	JP

PROJECTION:

APPROVAL: RJ

GENERAL TOLERANCE
.X = $^{+}/_{-}$ 0.2
.XX = $^{+}/_{-}$ 0.15

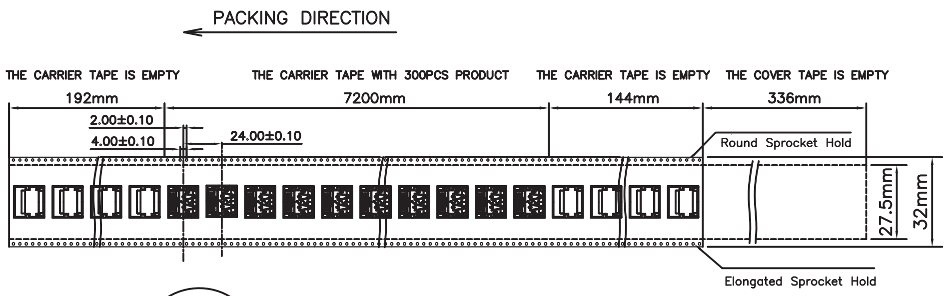
UNIT: MM
SCALE:
SHEET: 1/3
DRAW: JOE

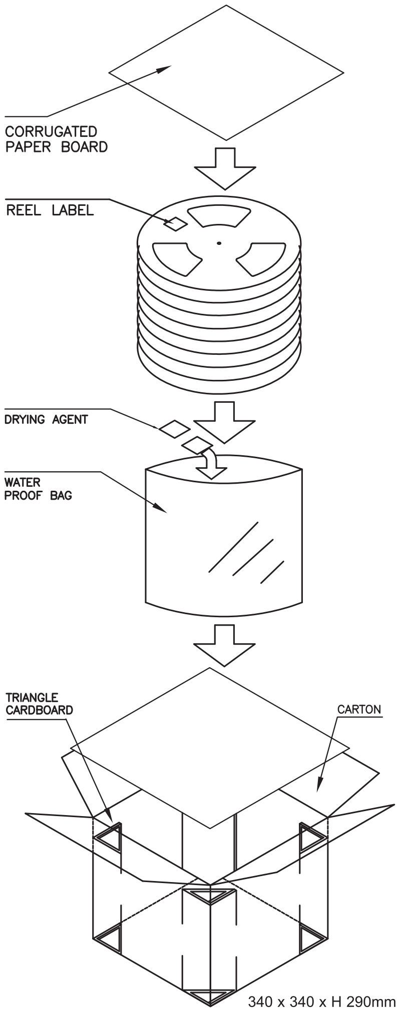
WÜRTH ELEKTRONIK

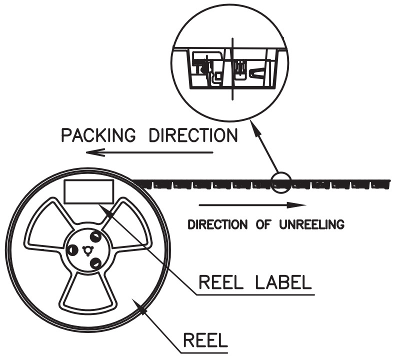
DESCRIPTION: USB 3.0 REVERSE HORIZONTAL TYPE A
WITH OFFSET 1.75 MM

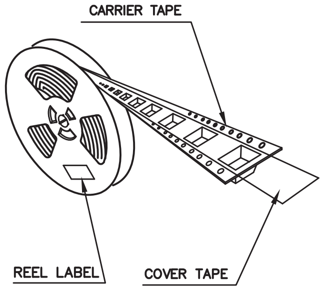
WERI PART NO: 692 121 330 100

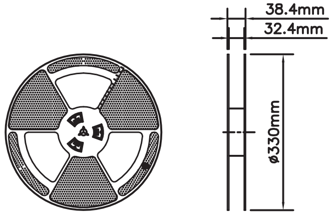
SIZE
A4











NOTES
1. MATERIALS: PS ANTI STATIC
2. PACKING:TAPE REEL(300PCS/REEL,2100PCS/CAR

All Material in According With The RoHS Environ
Related Substances List Controlled.

RoHS Compliant

G			
F			
E			
D			
C			
B			
A			
REV	DATE	FILE	BY

PROJECTION:

APPROVAL: RJ

GENERAL TOLERANCE
.X = $^{+}/_{-}$ 0.2
.XX = $^{+}/_{-}$ 0.15

UNIT: MM
SCALE:
SHEET: 2/3
DRAW: JOE

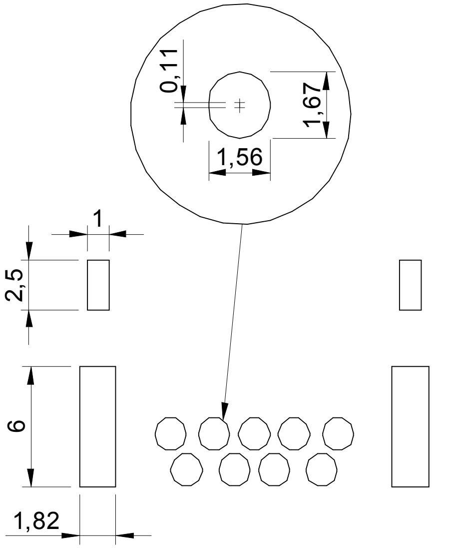
WÜRTH ELEKTRONIK

DESCRIPTION: USB 3.0 REVERSE HORIZONTAL TYPE A WITH OFFSET 1.75 MM

WERI PART NO: 692 121 330 100

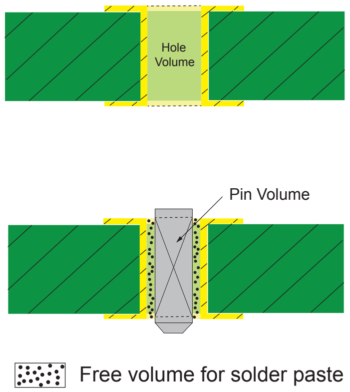
SIZE
A4

Stencil information for Through Hole Reflow soldering



STENCIL LAYOUT * - COMPONENT VIEW

PCB cross section



Theoritical Formula for Through Hole pins
Volume of the stencil aperture = (Hole volume - Pin volume) x 2
or
Volume of solder paste = (Hole volume - Pin volume) x 2

Stencil
Stencil Thickness: 150 µm

PCB
PCB thickness: 1.6mm

* NOTE: SEE PCB LAYOUT PAGE 1/3 FOR MISSING DIMENSIONS

RoHS Compliant

REV	DATE	FILE	BY
G			
F			
E			
D			
C			
B			
A			

PROJECTION:

APPROVAL: RJ

GENERAL TOLERANCE
.X = $^{+}/_{-}$ 0.2
.XX = $^{+}/_{-}$ 0.15

UNIT: MM
SCALE:
SHEET: 3/3
DRAW: JOE

WÜRTH ELEKTRONIK

DESCRIPTION: USB 3.0 REVERSE HORIZONTAL TYPE A WITH OFFSET 1.75 MM

WERI PART NO: 692 121 330 100

SIZE
A4